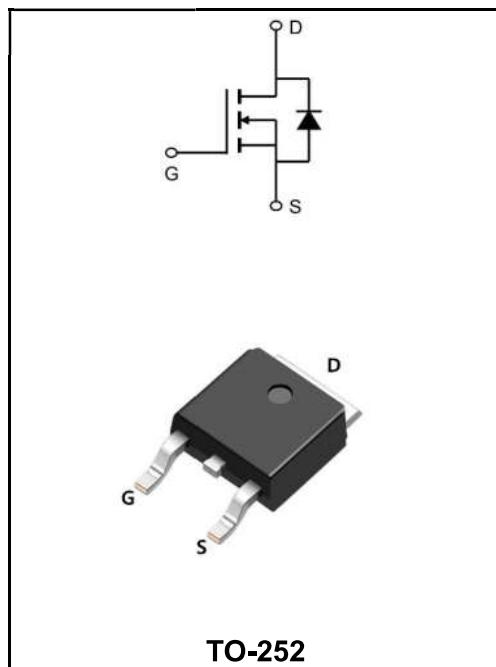


100V N-CHANNEL ENHANCEMENT MODE MOSFET
MAIN CHARACTERISTICS

I_D	40A
V_{DSS}	100V
$R_{DS(on)-typ}(@V_{GS}=10V)$	< 20mΩ (Type: 13.8 mΩ)


Application

- ◆ Consumer electronic power supply
- ◆ Motor control
- ◆ Synchronous-rectification
- ◆ Isolated DC
- ◆ Synchronous-rectification applications

Product Specification Classification

Part Number	Package	Marking	Pack
YFW40N10AD	TO-252	YFW 40N10AD XXXXX	2500PCS/Tape

Maximum Ratings at $T_c=25^\circ\text{C}$ unless otherwise specified

Characteristics	Symbols	Value	Units
Drain-Source Voltage	V_{DS}	100	V
Gate - Source Voltage	V_{GS}	± 20	V
Continuous drain current ¹⁾ , $T_c=25^\circ\text{C}$	I_D	40	A
Pulsed drain current ²⁾ , $T_c=25^\circ\text{C}$	$I_{D, \text{pulse}}$	120	A
Power dissipation ³⁾ , $T_c=25^\circ\text{C}$	P_D	71	W
Single Pulse Avalanche Energy ⁵⁾	E_{AS}	57	mJ
Operation and storage temperature	T_{STG}, T_J	-55 to +150	°C
Thermal Resistance, Junction-case	$R_{\theta JC}$	1.76	°C/W
Thermal Resistance, Junction-ambient ⁴⁾	$R_{\theta JA}$	62	°C/W

Maximum Ratings at Tc=25°C unless otherwise specified

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	BV _{DSS}	100	107	-	V
Gate -Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	V _{GS(th)}	1.2	1.5	2.5	V
Drain-source on-state resistance	V _{GS} =10V, I _D =10A	R _{DS(ON)}	-	13.8	20.0	mΩ
	V _{GS} =4.5V, I _D =7A		-	17.4	26.0	
Gate-Source Leakage Current	V _{GS} =±20V	I _{GSS}	-	-	±100	nA
Drain-Source Leakage Current	V _{DS} =100V , V _{GS} =0V	I _{DSS}	-	-	1	μA
Input Capacitance	V _{GS} =0V V _{DS} =50V f=100KHz	C _{iss}	-	1003.9	-	pF
Output Capacitance		C _{oss}	-	185.4	-	
Reverse Transfer Capacitance		C _{rss}	-	9.8	-	
Turn-on delay time	V _{GS} =10V V _{DS} =50V R _G =10Ω I _D =5A	t _{d(on)}	-	16.6	-	ns
Rise Time		T _r	-	3.8	-	
Turn-Off Delay Time		t _{d(OFF)}	-	75.5	-	
Fall Time		t _f	-	46	-	
Total Gate Charge	I _D =5A V _{DS} =50V V _{GS} =10V	Q _g	-	16.2	-	nC
Gate-Source Charge		Q _{gs}	-	2.8	-	
Gate-Drain Charge		Q _{gd}	-	4.1	-	
Gate plateau voltage		V _{plateau}	-	3	-	
Diode forward current	V _{GS} <V _{th}	I _s	-	30	-	A
Pulsed Source Current		I _{SP}	-	90	-	A
Reverse Recovery Time	I _s =1A , dI/dt=100A/μs	t _{rr}	49	-	-	ns
Reverse Recovery Charge		Q _{rr}	61.8	-	-	nC
Peak reverse recovery current		I _{rrm}	2.4	-	-	A

Note :

1. Calculated continuous current based on maximum allowable junction temperature.
2. Repetitive rating; pulse width limited by max. junction temperature.
3. Pd is based on max. junction temperature, using junction-case thermal resistance.
4. The value of R_{θja} is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with Ta=25 °C.
5. VDD=50 V, RG=25 Ω, L=0.3 mH, starting Tj=25 °C.

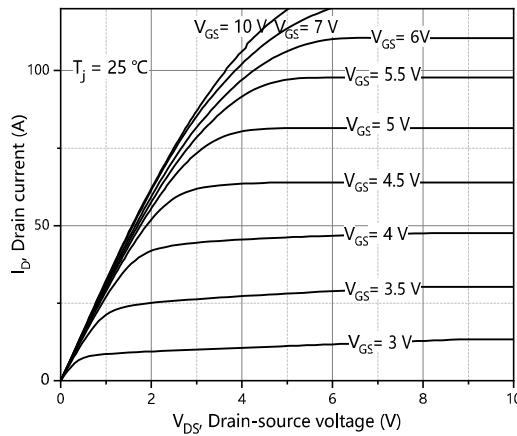
Ratings and Characteristic Curves
Typical Characteristics


Figure 1, Typ. output characteristics

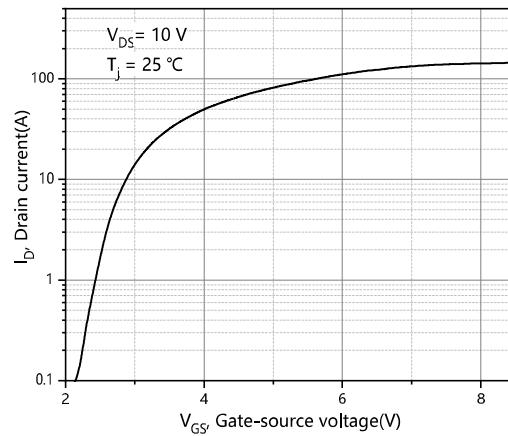


Figure 2, Typ. transfer characteristics

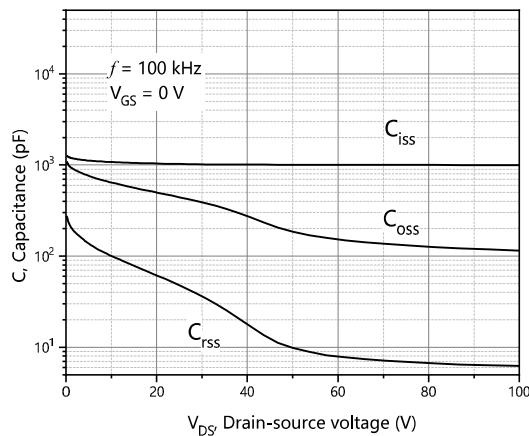


Figure 3, Typ. capacitances

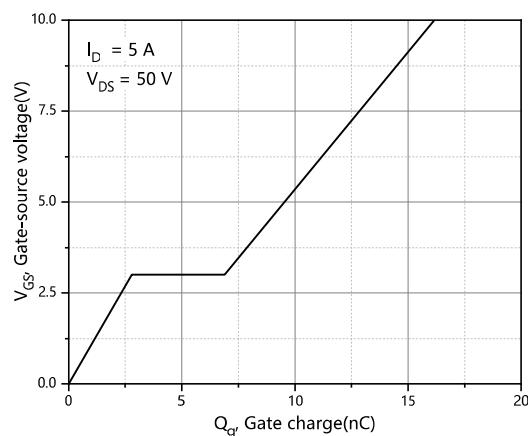


Figure 4, Typ. gate charge

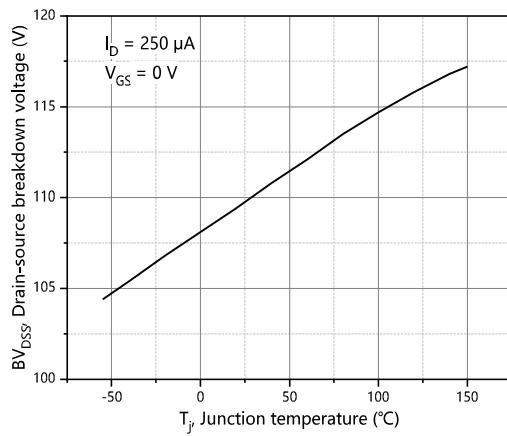


Figure 5, Drain-source breakdown voltage

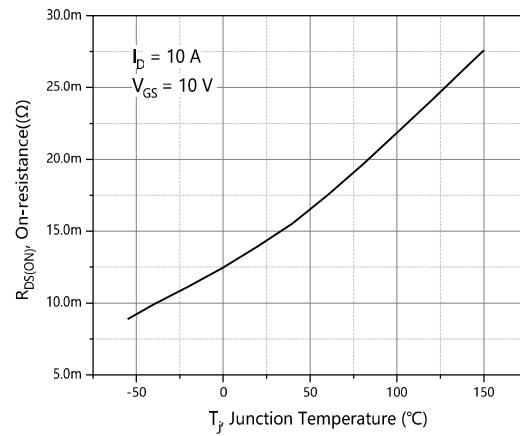


Figure 6, Drain-source on-state resistance

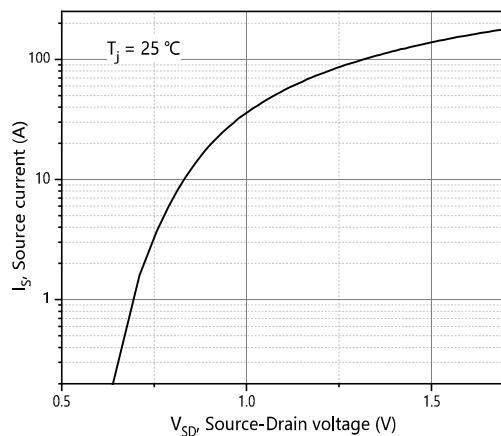
Ratings and Characteristic Curves


Figure 7, Forward characteristic of body diode

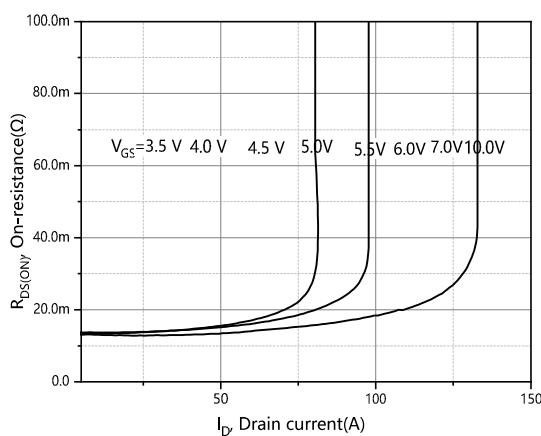


Figure 8, Drain-source on-state resistance

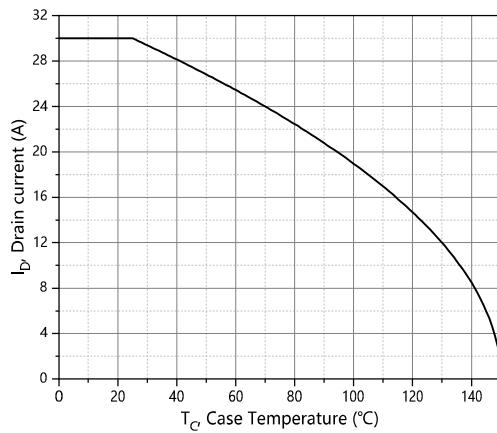


Figure 9, Drain current

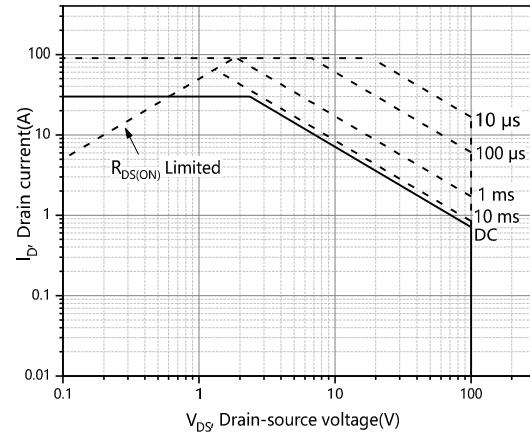


Figure 10, Safe operation area $T_C=25\text{ }^{\circ}\text{C}$

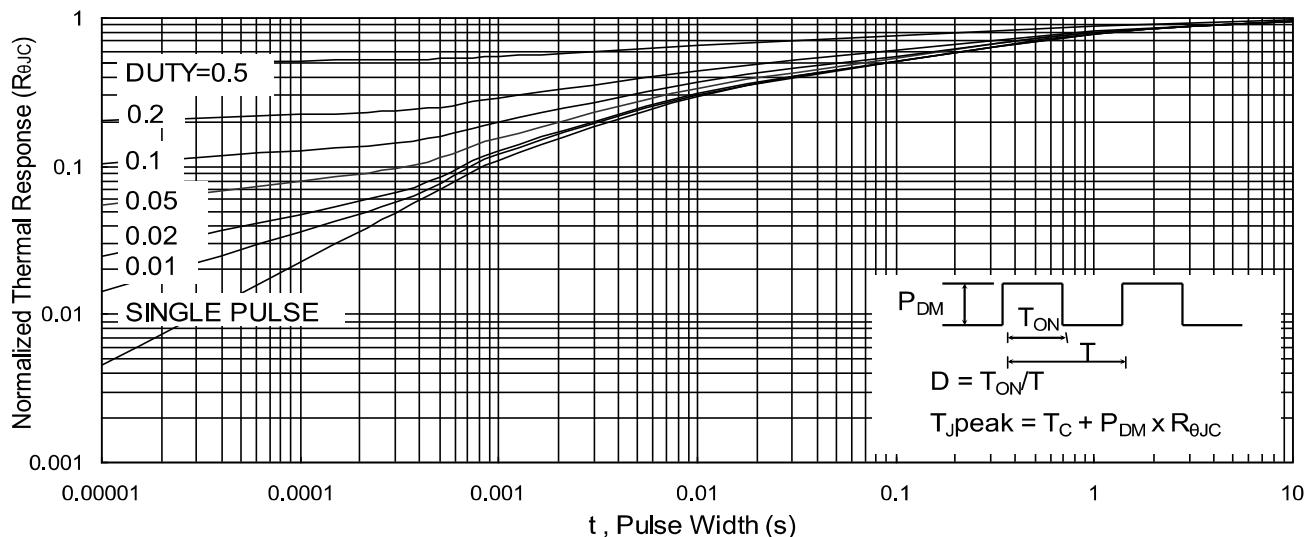
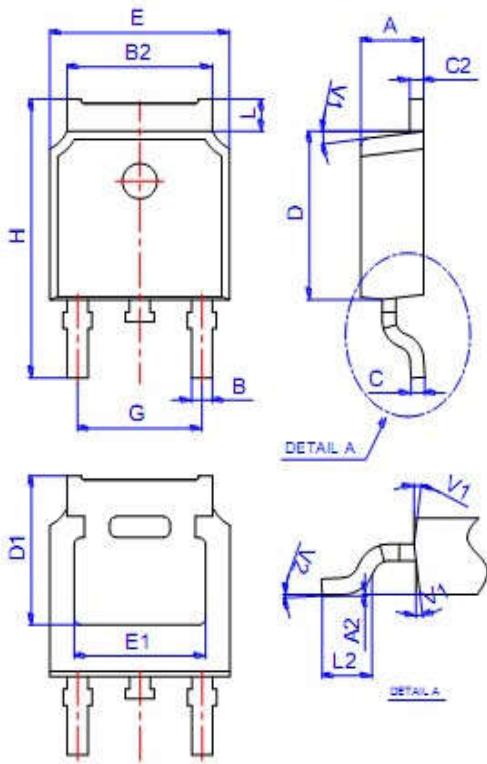


Fig11. Normalized Maximum Transient Thermal Impedance

Package Outline Dimensions Millimeters

TO-252



Dim.	Min.	Typ.	Max.
A	2.10	-	2.50
A2	0	-	0.10
B	0.66	-	0.86
B2	5.18	-	5.48
C	0.40	-	0.60
C2	0.44	-	0.58
D	5.90	-	6.30
D1	5.30REF		
E	6.40	-	6.80
E1	4.63	-	-
G	4.47	-	4.67
H	9.50	-	10.70
L	1.09	-	1.21
L2	1.35	-	1.65
V1	-	7°	-
V2	0°	-	6°

All Dimensions in millimeter